providing an insulating layer around an exterior surface of the cup-shaped bottom electrode, such that an entire vertical height of the exterior surface is in contact with the insulating layer;

masking a first portion of the insulating layer;

etching a second portion of the insulating layer from a first region of the exterior surface to expose the first region of the exterior surface, such that the insulating layer remains in contact with an entire vertical height of a remaining region of the exterior surface;

depositing a dielectric layer on the first region of the exterior surface; and

depositing a conductive layer on the dielectric layer.

REMARKS

Applicant has amended claims 29 and 67. Claims 29 and 67 remain for consideration in this application.

Rejection Under U.S.C. § 103

Claims 29 and 67 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Dennison (U. S. Patent No. 5,362,666).

Referring to claim 29, the claim as amended recites, in part, "masking a first partial circumferential portion of said insulating layer." This process of masking and the subsequently recited etching is neither taught nor disclosed in Dennison, as Dennison performs an etch to remove the supporting insulator 32 to a uniform depth for the entire circumference of the container. (See Figs. 4-5 and col. 10).

Referring to claim 67, the claim as amended recites, in part, "etching a second portion of the insulating layer from a first region of the exterior surface to expose the first region of the exterior surface, such that the insulating layer remains in contact with an entire vertical height of a remaining region of the exterior surface." This is clearly distinguished from the structure of Dennison which exposes at least a part of the exterior vertical surface of the bottom electrode for the entire bottom electrode.

CONCLUSION

In view of the above amendments and remarks, Applicant respectfully submits that all claims are in condition for allowance and requests reconsideration of the application and allowance of claims. The Examiner is invited to contact Applicant's attorney to discuss any questions that may remain with respect to the present application.

Respectfully submitted,

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By their Representatives,

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MARKED-UP VERSION OF AMENDMENTS

IN THE CLAIMS

29. (Amended) A method for forming a container capacitor, comprising the steps of:

providing a cup-shaped bottom electrode;

providing an insulating layer around and in contact with an exterior surface of said cup-shaped bottom electrode;

masking a first partial circumferential portion of said insulating layer;

etching a second portion of said insulating layer from a second partial circumferential part of said exterior surface to expose the part of said exterior surface;

depositing a dielectric layer on said part of said exterior surface; and

depositing a conductive layer on said dielectric layer.

67. (Amended) A method for forming a container capacitor comprising:

fabricating a cup-shaped bottom electrode;

providing an insulating layer around an exterior surface of the cup-shaped bottom electrode, such that an entire vertical height of the exterior surface is in contact with the insulating layer;

masking a first portion of the insulating layer;

etching a second portion of the insulating layer from a first region of the exterior surface to expose the first region of the exterior surface, such that the insulating layer remains in contact with an entire vertical height of a remaining region of the exterior surface;

depositing a dielectric layer on the first region of the exterior surface; and

depositing a conductive layer on the dielectric layer.